

LIST OF REFERENCES CITED BY APPLICANT Form PTO-1449 <i>(Use several sheets if necessary)</i>					ATTY. DOCKET NO.: 4717-8900		APPLICATION NO.: 10/663,917		
<div style="position: relative; height: 100px;"> <div style="position: absolute; top: 0; left: 0; width: 100%; height: 100%; border: 1px solid black; border-radius: 50%; text-align: center; line-height: 100px; font-size: 24px; font-weight: bold;"> O I P E APR 27 2004 PATENT & TRADEMARK DEPT. </div> </div>					APPLICANT: Tukeshi AKATSU et al.				
Sheet 1 of 1					FILING DATE: September 17, 2003		GROUP: 2811		
U.S. PATENT DOCUMENTS									
*EXAMINER INITIAL	CITE NO.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE		
	A1	6,100,166	08/2000	Sakaguchi et al.	438	455			
	A2	2002/0125497 A1	09/2002	Fitzgerald	257	191			
	A3	2002/0123183 A1	09/2002	Fitzgerald	438	199			
	A4	6,521,041 B2	02/2003	Wu et al.	117	94			
	A5	6,534,382 B1	03/2003	Sakaguchi et al.	438	455			
	A6	2003/0077867	04/2003	Fitzgerald	438	285			
	A7	6,593,641 B1	07/2003	Fitzgerald	257	616			
	A8	2003/0203547 A1	10/2003	Sakaguchi et al.	438	151			
	A9	6,646,322 B2	11/2003	Fitzgerald	257	531			
	A10	2004/0000268 A1	01/2004	Wu et al.	11	94			
	A11	6,677,192 B1	01/2004	Fitzgerald	438	172			
FOREIGN PATENT DOCUMENTS									
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION		
							YES	NO	
	B1	WO 99/53539 A	10/1999	WIPO					
	B2	WO 02/071495 A	12/2002	WIPO					
OTHER REFERENCES <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i>									
	C1	Cheng, Z-Y et al., "SiGe-On-Insulator (SGOI): Substrate Preparation and MOSFET Fabrication for Electron Mobility Evaluation," IEEE International SOI Conference, pp. 13-14, October 2001							
	C2	Tong, Q.Y. et al., "Semiconductor Wafer Bonding" (extracts), Science and Technology, Interscience Technology, November 1998							
EXAMINER					DATE CONSIDERED 11/12/04				
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.									

